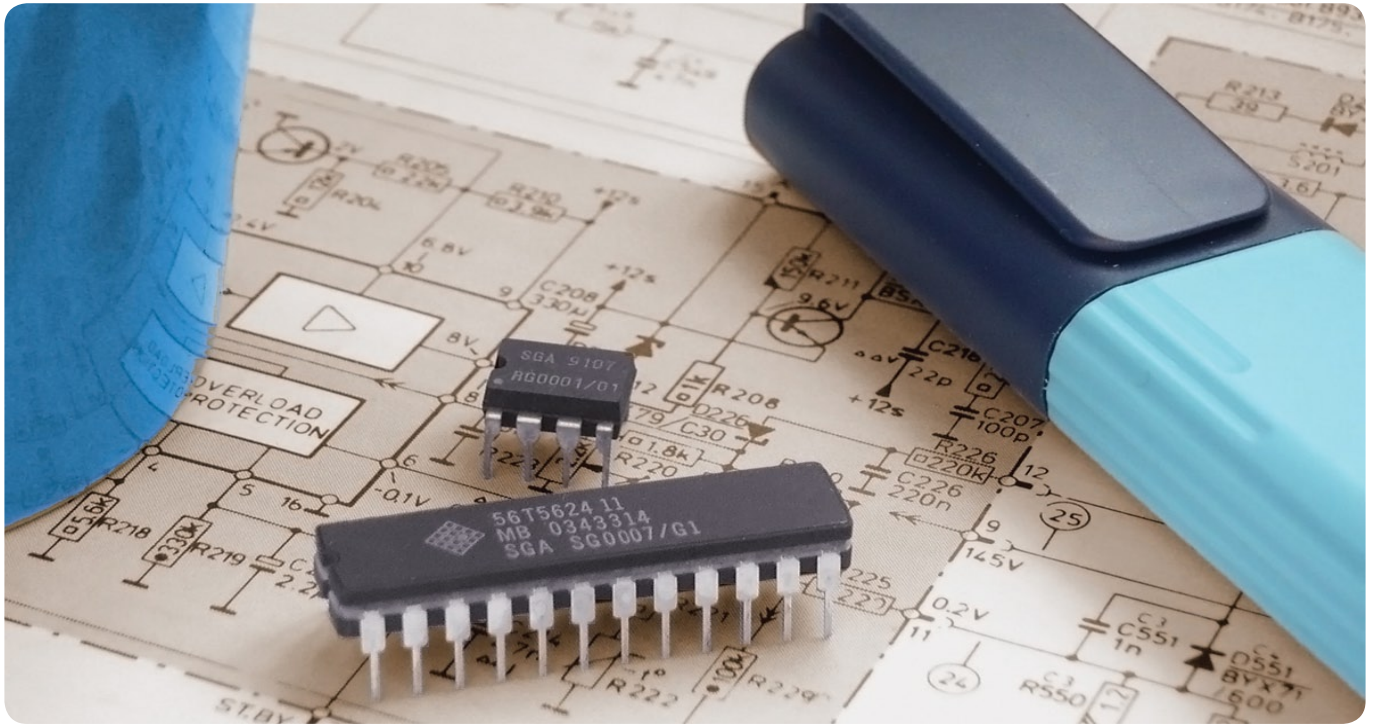




Managing a Last Time Buy



Last Time Buy situations are unfortunately not very rare for integrated circuits. Re-design of a product because of an LTB for a component is a tedious and not very productive task.

A Specific Component from SGA can be designed as a drop-in replacement for an obsolete component and will in this way solve the LTB-problem.

It can happen to anyone at anytime. Your product has been in production for a while and suddenly you get a message from one of your component suppliers. You are told that one component is on its way to obsolescence and you are instructed you to do a Last Time Buy.

You may consider your problem to be even worse if your component is an ASIC. You then probably have one single source and finding a direct replacement on the market is not possible. There is no need for panic. SGA can solve your LTB-problems.

Replace

It is in many cases very hard to estimate future need for a component when you get a Last Time Buy. This is even more so when the expected lifetime for the application that uses the component is long. Placing an order for the remaining life of the application is then not an alternative and you need to find a new solution.

Re-design of a system where an important component is not longer available can be a difficult task. One change affects something else and you end up with a chain of actions that requires huge efforts to sort out.

specific  **components**



We have extensive experience from designing replacement Specific Components that are fully compatible with existing parts that have turned obsolete. The main advantage with this approach is naturally that we provide a drop-in replacement component. Other parts of the system can therefore be left as they are. Your re-design efforts are in this way minimized.

Die Bank

A valid solution for a product with low expected production volume or short remaining lifetime is to stock the remaining quantity when a last time buy occurs. It is then an advantage to keep this stock at wafer level as cost for assembly and final test is not included in the stocked material. This type of stock is referred to as a Die Bank.

SGA currently keeps Die Banks for several products. The stock consists of tested dies on wafer. This gives that it is possible to accurately estimate the number of components that can be delivered. All cost for assembly, final test and maybe also screening will only occur as components are manufactured from the Die Bank. The total value of the goods in stock is minimized.

Continuity

We can not totally protect our customers from LTB:s. Expected life is an important issue when we select a manufacturing process for our customers designs. Every process will however finally be discontinued and replaced and this is a part of the constantly ongoing evolution in this industry.

We will do what is needed to solve any issue that arises from LTB:s generated by our suppliers. It is our business to provide our customers with components and we will not let an LTB from a vendor stop us. A proper combination of Die Bank and design of replacement components will guarantee continuity in the deliveries to our customers.

Contact SGA for LTB-related issues